HALOGEN

FREE

Vishay Techno



www.vishay.com

Thick Film Chip Resistors, High Voltage



LINKS TO ADDITIONAL RESOURCES



FEATURES

- High voltage up to 3000 V
- Outstanding stability < 0.5 %
- Flow solderable
- Custom sizes available
- Automatic placement capability
- Tape and reel packaging available
- Termination style: 3-sided wraparound termination or single termination flip chip standard; 5-sided wraparound termination available
- Internationally standardized sizes
- Suitable for solderable, epoxy bondable, or wire bondable applications
- Termination material: solder-coated nickel barrier or solder coated non-magnetic terminations standard; gold, palladium silver, platinum gold, platinum silver or platinum palladium gold terminations available
- Multiple styles, termination materials and configurations, allow wide design flexibility
- Epoxy bondable or wire bondable non-magnetic terminations available
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

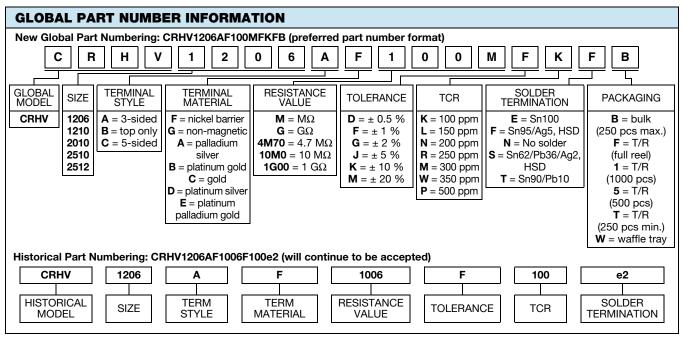
This datasheet provides information about parts that are RoHS-compliant and/or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

STANDARD ELECTRICAL SPECIFICATIONS						
GLOBAL MODEL	CASE SIZE	POWER RATING P _{70 °C} W	MAXIMUM WORKING VOLTAGE ⁽¹⁾ V	RESISTANCE RANGE ⁽²⁾	TOLERANCE (3) ± %	TEMPERATURE COEFFICIENT ⁽⁴⁾ (-55 °C to +155 °C) ± ppm/°C
				2M to 100M	0.5	
CRHV1206	1206	0.30	1500	2M to 1G	1, 2, 5, 10, 20	100
				1.1G to 8G	2, 5, 10, 20	
				4M to 100M	0.5	
CRHV1210	1210	0.45	1750	4M to 1G	1, 2, 5, 10, 20	100
				1.1G to 10G	2, 5, 10, 20	
				6M to 100M	0.5	
ODLIV0010	2010	0.50	2000	6M to 1G	1, 2, 5, 10, 20	100
CRHV2010				1.1G to 10G	2, 5, 10, 20	
				11G to 35G	5, 10, 20	
				10M to 100M	0.5	
ODLIV0510	0510	0.00	2500	10M to 1G	1, 2, 5, 10, 20	100
CRHV2510	2510	0.60	2500	1.1G to 10G	2, 5, 10, 20	100
				11G to 40G	5, 10, 20	
CRHV2512	2512	1.0	3000	10M to 100M	0.5	100
				10M to 1G	1, 2, 5, 10, 20	
				1.1G to 10G	2, 5, 10, 20	
				11G to 50G	5, 10, 20	

Notes

- For non-standard sizes, lower values or higher power rating requirement, contact factory
- Continuous working voltage shall be $\sqrt{P \times R}$ or maximum working voltage, whichever is less
- Resistance values below 1 G Ω are calibrated at 100 V_{DC}, and values of 1 G Ω and above are calibrated at 1000 V_{DC}. Calibration at other voltages available upon request
- Contact factory for tighter tolerances
- (4) Reference only: not for all values specified. Consult factory for your size and value. The TC for "AA" option is typically 200 ppm



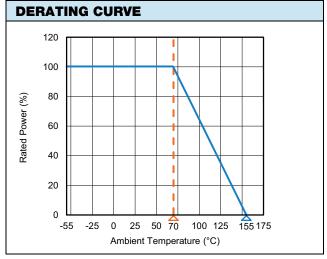


Note

For additional information on packaging, refer to the Surface Mount Resistor Packaging document (<u>www.vishay.com/doc?31543</u>)

MECHANICAL SPECIFICATIONS			
Resistive element	Ruthenium oxide		
Encapsulation	Glass		
Substrate	96 % alumina		
Termination	Solder-coated nickel barrier or solder coated non-magnetic terminations standard. Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold terminations available.		
Solder finish	Pure tin or tin/lead solder alloys standard. Tin/silver or tin/lead/silver solder alloys available.		

ENVIRONMENTAL SPECIFICATIONS			
Operating temperature	-55 °C to +155 °C		
Life	Less than 0.5 % change when tested at full rated power		
Short time overload	Less than 0.5 % ΔR		



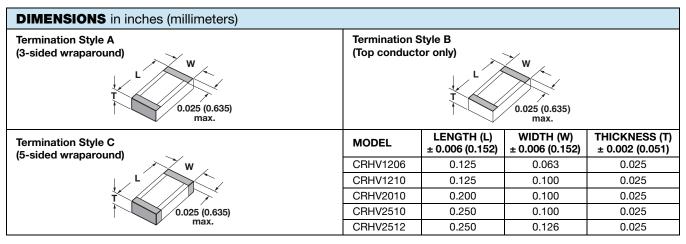
Note

 Reference only: Not for all values specified. Consult factory for your size and value

VOLTAGE COEFFICIENT OF RESISTANCE CHART				
SIZE	VALUE (Ω)	VCR (ppm/V)	FURTHER INSTRUCTIONS	
CRHV1206	2M to 199M	25	Values over 200M, consult factory	
CRHV1210	4M to 200M	25	Values over 200M, consult factory	
CRHV2010	6M to 99M	15	Values over 1G, consult factory	
Chriv2010	100M to 1G	20	values over 1G, consult factory	
CRHV2510	10M to 99M	10	Values over 1G, consult factory	
	100M to 1G	15		
CRHV2512	10M to 999M	10	Values over 5G, consult factory	
	1G to 5G	25		

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TYPE	TERMINATION MATERIAL	TERMINATION STYLE	TERMINATION STYLE / MATERIAL CODE	SOLDER TERMINATION CODE	
Solderable		3-sided (wraparound)	AF	E or T (standard); F or S (optional) ⁽³⁾	
	Nickel barrier	Top only (flip chip)	BF		
		5-sided (wraparound)	CF		
	N	3-sided (wraparound)	AG	E or T (standard); F or S (optional) ⁽³⁾	
	Non-magnetic	Top only (flip chip)	BG		
Face basedable /		3-sided (wraparound)	AE		
Epoxy bondable / solderable	Platinum palladium gold	Top only (flip chip)	BE	N (standard); F or S (optional) ⁽¹⁾	
		5-sided (wraparound)	CE	r or 3 (optional) (7	
MAC as to a salada la d	Gold	3-sided (wraparound)	AC		
Wire bondable / Epoxy bondable		Top only (flip chip)	BC	N	
		5-sided (wraparound)	CC		
Epoxy bondable		3-sided (wraparound)	AA		
	Palladium silver (2)	Top only (flip chip)	BA		
		5-sided (wraparound)	CA		
	Platinum gold	3-sided (wraparound)	AB		
		Top only (flip chip)	BB	N	
		5-sided (wraparound)	СВ		
		3-sided (wraparound)	AD		
	Platinum silver	Top only (flip chip)	BD		
		5-sided (wraparound)	CD		

Notes

(1) Use solder termination N for applications requiring epoxy bondable mounting, and solder terminations F or S for applications requiring solderable mounting

(3) Standard solder plating for the nickel barrier and non-magnetic parts is solder terminations E or T. Hot solder dipped terminations F or S are also available

PERFORMANCE				
TEST	CONDITIONS OF TEST	TEST RESULTS (TYPICAL TEST LOTS)		
Life	MIL-STD-202, method 108, 1000 h rated power at +70 °C	≤ ± 0.5 %		
High temperature exposure	MIL-STD-202, method 108	≤± 0.2 %		
Low temperature operation	MIL-PRF-55342, paragraph 4.8.5	≤ ± 0.05 %		
Resistance to bonding exposure	MIL-STD-202, methods 210	≤ ± 0.1 %		
Moisture resistance	MIL-PRF-55342, paragraph 4.8.9	≤ ± 0.06%		
Solder mounting integrity	MIL-PRF-55342, paragraph 4.8.13, 2 kg for 30 s	No evidence of mechanical damage		
Solderability	MIL-STD-202, method 208	95 % coverage		

Note

- This summary is based on testing done on values up to 2 $\mbox{G}\Omega$

⁽²⁾ While not recommended, palladium silver terminations could be used for solderable applications when using a solder alloy containing silver. If the solder paste being used to solder the palladium silver terminated parts to the boards does not have a silver-based composition, then the silver in the terminations could begin to leach when it is exposed to liquidus non-silver-based solders, causing the potential for solderability and/or solder joint issues



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